

Global Epoxy Resin Encapsulation Adhesive for Electronic Products Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Epoxy Resin Encapsulation Adhesive for Electronic Products market size is expected to reach \$ 2465 million by 2032, rising at a market growth of 6.3% CAGR during the forecast period (2026-2032).

In 2025, the global production of epoxy resin encapsulation adhesive for electronic products reached approximately 189,100 tons, with an average global market price of around US\$8,000/ton. In the same year, the global total production capacity of epoxy resin encapsulation adhesive for electronic products reached 20,000 tons. The industry average gross profit margin of this product reached 36%. Epoxy resin encapsulation adhesive for electronic products is an electronic encapsulation material made primarily of epoxy resin, combined with curing agents, fillers, accelerators, flame retardants, and functional additives. It is mainly used for encapsulation, potting, underfilling, and protection of semiconductors, PCBs, power modules, LEDs, automotive electronics, sensors, IGBTs, and consumer electronics devices. Its core function is to provide electronic components with insulation, moisture protection, corrosion resistance, thermal shock resistance, mechanical protection, and thermal management capabilities, thereby improving the reliability and lifespan of electronic products. As electronic devices evolve towards higher power, miniaturization, higher frequency and speed, and higher integration, modern epoxy encapsulation adhesives have evolved from traditional protective materials into key functional materials affecting chip heat dissipation, signal stability, and long-term reliability.

The upstream of the epoxy resin encapsulation adhesive for electronic products industry chain mainly includes suppliers of epoxy resins, curing agents, silica powder, alumina, boron nitride and other fillers, as well as flame retardants, coupling agents and

functional additives. The midstream consists of encapsulation adhesive manufacturers responsible for formulation design, modification, mixing, low-stressing, high thermal conductivity and semiconductor-grade purification. The downstream covers semiconductor packaging and testing, power devices, automotive electronics, LEDs, consumer electronics, industrial control, communication equipment, AI servers and new energy fields. Currently, the industry's technological barriers are mainly concentrated in low CTE, high thermal conductivity, high flowability, low ionic impurities, high reliability and advanced packaging compatibility. Therefore, leading companies usually possess material formulation, application verification and customer certification capabilities.

From an industry outlook perspective, the epoxy resin encapsulation adhesive for electronic products industry is in a continuous upgrading phase, with growth driven primarily by the development of AI chips, advanced packaging, new energy vehicles, electric drive systems, SiC/GaN power semiconductors, 5G base stations and high-performance computing. The rapidly increasing demand for high thermal conductivity, low warpage, and low stress EMC, particularly in HBM, GPUs, AI servers, and automotive power modules, has made advanced packaging EMC one of the fastest-growing segments. Future industry development will focus on new material systems that offer high thermal conductivity, are green and halogen-free, have ultra-low dielectric properties, high resistance to humidity and heat, and are compatible with Chiplet and advanced heterogeneous packaging. Asia, especially mainland China, Taiwan, Japan, and South Korea, will continue to dominate global demand and production capacity.

This report studies the global Epoxy Resin Encapsulation Adhesive for Electronic Products production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Epoxy Resin Encapsulation Adhesive for Electronic Products and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Epoxy Resin Encapsulation Adhesive for Electronic Products that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Epoxy Resin Encapsulation Adhesive for Electronic Products total production and demand, 2021-2032, (Tons)

Global Epoxy Resin Encapsulation Adhesive for Electronic Products total production value, 2021-2032, (USD Million)

Global Epoxy Resin Encapsulation Adhesive for Electronic Products production by

region & country, production, value, CAGR, 2021-2032, (USD Million) & (Tons), (based on production site)

Global Epoxy Resin Encapsulation Adhesive for Electronic Products consumption by region & country, CAGR, 2021-2032 & (Tons)

U.S. VS China: Epoxy Resin Encapsulation Adhesive for Electronic Products domestic production, consumption, key domestic manufacturers and share

Global Epoxy Resin Encapsulation Adhesive for Electronic Products production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Tons)

Global Epoxy Resin Encapsulation Adhesive for Electronic Products production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

Global Epoxy Resin Encapsulation Adhesive for Electronic Products production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

This report profiles key players in the global Epoxy Resin Encapsulation Adhesive for Electronic Products market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include 3M, Henkel, Parker LORD, SolEpoxy, Epic Resins, Robnor ResinLab, Guangdong Anders Industrial Co., Ltd., Shantou Niche-Tech Kaiser Co., Ltd., Dongguan Huachuang Electronic Materials Co., Ltd., Guangdong Wanmu New Material Technology Co., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Epoxy Resin Encapsulation Adhesive for Electronic Products market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Tons) and average price (US\$/Ton) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Epoxy Resin Encapsulation Adhesive for Electronic Products Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Epoxy Resin Encapsulation Adhesive for Electronic Products Market,
Segmentation by Type:

One-component

Two-component

Global Epoxy Resin Encapsulation Adhesive for Electronic Products Market,
Segmentation by Curing Method:

Room Temperature Curing

Heat Curing

UV Curing

Others

Global Epoxy Resin Encapsulation Adhesive for Electronic Products Market,
Segmentation by Resin System:

Bisphenol A Type

Phenolic Novolac Type

Biphenyl Type

Cyanate Ester Modified Type

Siloxane Modified Type

Global Epoxy Resin Encapsulation Adhesive for Electronic Products Market,
Segmentation by Application:

Consumer Electronics

Automotive Electronics

Medical Electronics

Industrial

Others

Companies Profiled:

3M

Henkel

Parker LORD

SolEpoxy

Epic Resins

Robnor ResinLab

Guangdong Anders Industrial Co., Ltd.

Shantou Niche-Tech Kaiser Co., Ltd.

Dongguan Huachuang Electronic Materials Co., Ltd.

Guangdong Wanmu New Material Technology Co., Ltd.

Beijing Kmt Technology Co., Ltd

Yongdeji Technology (Suzhou) Co., Ltd.

Shanghai Dodi Polymer Material Co., Ltd.

Hubei Huitian New Materials Co., Ltd.

Dongguan Sains Industrial Co., Ltd.

Shin-Etsu Chemical

Sumitomo Bakelite

NAMICS Corporation

Resonac

Master Bond

Epoxy Technology

EpoxySet

United Resin

DELO

Panacol

Electrolube

Bostik

Key Questions Answered:

1. How big is the global Epoxy Resin Encapsulation Adhesive for Electronic Products market?
2. What is the demand of the global Epoxy Resin Encapsulation Adhesive for Electronic Products market?
3. What is the year over year growth of the global Epoxy Resin Encapsulation Adhesive for Electronic Products market?
4. What is the production and production value of the global Epoxy Resin Encapsulation Adhesive for Electronic Products market?
5. Who are the key producers in the global Epoxy Resin Encapsulation Adhesive for Electronic Products market?
6. What are the growth factors driving the market demand?

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